



US 20230232598A1

(19) **United States**
(12) **Patent Application Publication** (10) **Pub. No.: US 2023/0232598 A1**
GAO et al. (43) **Pub. Date: Jul. 20, 2023**

(54) **POWER SUPPLY UNIT, LIQUID COOLED ENCLOSURE AND METHOD THEREOF**

Publication Classification

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(51) **Int. Cl.**
H05K 7/20 (2006.01)

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(52) **U.S. Cl.**
CPC **H05K 7/20927** (2013.01); **H05K 7/209** (2013.01); **H05K 7/20263** (2013.01)

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(57) **ABSTRACT**

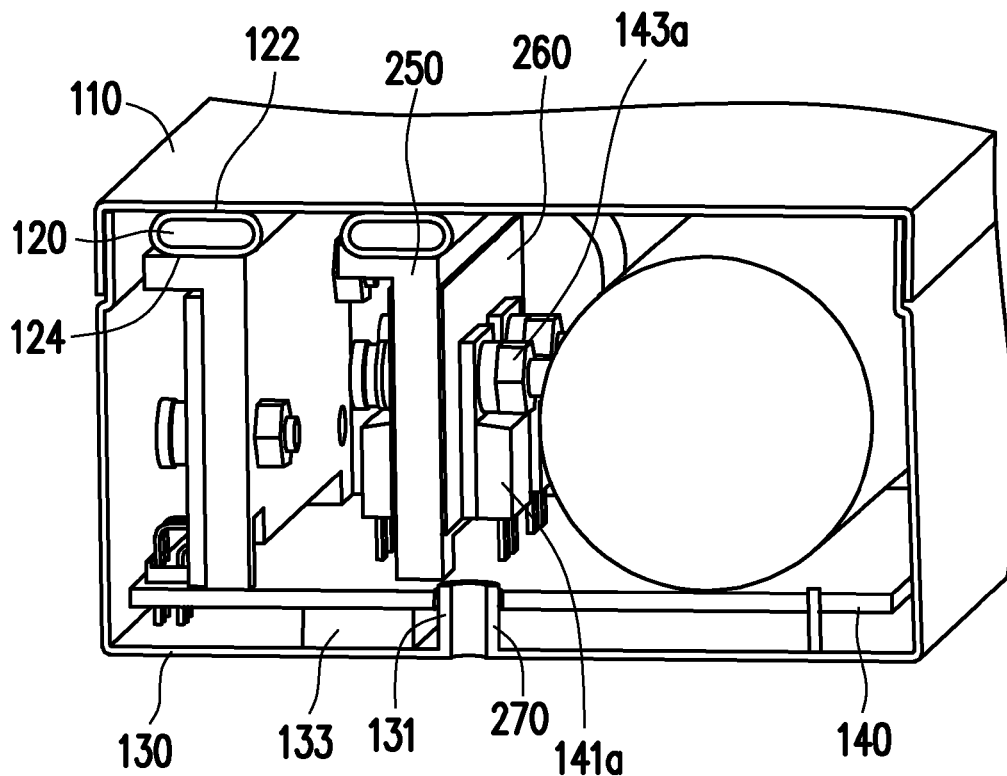
(21) Appl. No.: **17/726,520**

(22) Filed: **Apr. 21, 2022**

Related U.S. Application Data

(60) Provisional application No. 63/299,413, filed on Jan. 14, 2022.

A liquid cooled enclosure for transfer heat from a printed circuit board assembly (PCBA) which is disposed inside the liquid cooled enclosure is introduced. The liquid cooled enclosure includes a first cover structure, a cooler structure and a second cover structure. The cooler structure, which is mounted on the first cover structure, includes a hollow tube with a predefined shape pattern. The second cover structure includes an elastic pad that is disposed on a surface of the second cover structure. The PCBA is floatingly mounted on the elastic pad of the second cover structure, and the elastic pad is configured to push the PCBA toward the cooler structure such that heat from the PCBA is dissipated via the cooler structure.



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